Overview



Front

- 1. Pull-up webcam and microphone
- 2. Speakers

3. SD media card reader (optional)

Overview

HP 200 (Pro) G4 22 All-in-One PC



Rear

- 1. Optical disc drive (optional)
- 2. Power button
- 3. Pull-up webcam
- 4. Microphone/Headphone Combo Jack
- 5. RJ-45 (network) jack

- 6. HDMI 1.4 out connector
- 7. Power connector
- 8. Two (2) Type-A Hi-Speed USB 480Mbps signaling rate ports
- 9. Two (2) Type-A SuperSpeed USB 5Gbps signaling rate port
- 10. Standard cable lock slot

Features

AT A GLANCE

- Choice of Windwos 11 Pro, Windows 11 Home, Windows 10 Pro, and FreeDOS
- Integrated All-in-One form factor
- 21.5-inch diagonal widescreen Full HD anti-glare display
- Intel® 12th generation processors, featuring optional Intel® Iris® Xe and integrated Intel® UHD Graphics
- Up to 32GB 3200MT/s of DDR4 Synchronous Dynamic Random-Access Memory (SDRAM)
- Integrated 10/100/1000 Gigabit LAN Ethernet Controller
- Optional Wi-Fi 5 (802.11ac) wireless connectivity
- Integrated HD audio card and stereo speakers
- Integrated 5MP pull-up camera to ensure no accidental recording to safeguard user's privacy
- Expandable storage options with up to 512GB SSD and 2TB HDD
- Optional HP Slim Tray DVD Writer 8X Optical Drive
- Optional 3-in-1 Media Card Reader
- TPM 2.0 support
- Low halogen¹ materials,
- Protected by HP Services. Terms and conditions vary by country. Certain restrictions and exclusions apply.

1. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

NOTE: See important legal disclosures for all listed specs in their respective features sections.





Features

OPERATING SYSTEMS

Preinstalled Windows 11 Pro¹

Windows 11 Pro Education¹

Windows 11 Home - HP recommends Windows 11 Pro for business¹

Windows 10 Pro^{1,2}

Pre-installed (other) FreeDOS

1. Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

2. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed interneet and Microsoft account required. ISP fees apply and additional requirements may apply over time for updates. See http://www.windows.com.

PROCESSORS*

Intel® 12th Generation Core™ Processors

Intel® Core™ i5-1235U Processor
0.9 GHz E-core 1.3 GHz P-core base frequency, up to 3.3 GHz E-core 4.4 P-core Max Turbo frequency
12 MB L3 cache, 10 cores, 12 threads
Integrated Intel® Iris® X® Graphics
Supports DDR4 memory up to 3200MT/s data rate

Intel® Core™ i3-1215U
0.9 GHz E-core 1.2 GHz P-core base frequency, up to 3.3 GHz E-core 4.4 P-core Max Turbo frequency
10 MB L3 cache, 6 cores, 8 threads
Integrated Intel® UHD Graphics
Supports DDR4 memory up to 3200MT/s data rate

Intel® 10th Generation Core™ Processors

Intel® Core™ i5-10210U Processor
1.6 GHz base frequency
Up to 4.2 GHz max. turbo frequency with Intel® Turbo Boost**
6 MB cache, 4 cores, 8 threads
Intel® UHD Graphics
Supports DDR4 memory up to 2666 MT/s data rate

Intel® Core™ i3-10110U Processor
2.1 GHz base frequency
Up to 4.1 GHz max. turbo frequency with Intel® Turbo Boost**
4 MB cache, 2 cores, 4 threads
Intel® UHD Graphics
Supports DDR4 memory up to 2666 MT/s data rate

Intel® Pentium® Processors

Intel® Pentium® Silver J5040 Processor
2.0 GHz base frequency
Up to 3.2 GHz max. turbo frequency with Intel® Turbo Boost**
4 MB cache, 4 cores, 4 threads
Intel® UHD Graphics 605
Supports DDR4 memory up to 2400 MT/s data rate



Features

*Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

**Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

NOTE: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



Features

GRAPHICS

Integrated

Intel® Iris® X® Graphics Intel® UHD Graphics Intel® UHD Graphics 605

NOTE: Intel® integrated UHD Graphics varies by processor

DISPLAY

Non-Touch

21.5" diagonal FHD IPS anti-glare WLED-backlit (1920 x 1080) 21.5" diagonal FHD VA anti-glare WLED-backlit (1920 x 1080)

STORAGE AND DRIVES¹

M.2 PCIe NMVe Solid State Drives (SSD)

256GB 2280 PCIe NVMe Solid State Drive 512GB 2280 PCIe NVMe Solid State Drive 128GB 2280 PCIe NVMe TLC Solid State Drive 256GB 2280 PCIe NVMe TLC Solid State Drive 512GB 2280 PCIe NVMe TLC Solid State Drive

3.5 inch 7200RPM SATA Hard Disk Drives (HDD)

500GB 7200RPM 3.5in HDD 1TB 7200RPM 3.5in HDD 2TB 7200RPM 3.5in HDD

Optical Disc Drives

9.5mm Ultra Slim DVD-Writer

Media Card Reader (Optional)

SD Card Reader with 3-in1 Interface (Supports SD, SDHC, SDXC)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum

DDR4 SODIMM up to 3200 MT/s

Memory Slots

2 SODIMM

Available Configurations

4GB (4GB x1) 8GB (4GB x2) 8GB (8GB x1)

16GB (8GB x2)

16GB (16GB x1)

32GB (16GB x2)

NOTE: Actual data rate is determined by both the system's configured processor and memory module installed.

NETWORKING/COMMUNICATIONS



Features

Wireless LAN*

Realtek® RTL8822CE Wi-Fi 5¹ (802.11ac) 2x2 Wi-Fi M.2 Card² Realtek® RTL8821CE Wi-Fi 5¹ (802.11ac) 1x1 Wi-Fi M.2 Card²

Ethernet (RJ-45) Integrated

Realtek® RTL8111HSH-CG Gigabit Ethernet Controller

*Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 is backwards compatible with prior 802.11 specs.

- 1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.
- 2. Must be configured at time of purchase.

AUDIO/MULTIMEDIA

High Definition Audio

Integrated Realtek ALC3247 Audio Codec High performance integrated stereo speakers 3.5mm combo (microphone/headphone) jack

Webcams & Mic

Integrated 5MP webcam, Up to 30 frames/sec, dual array microphone included

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboards

HP Universal USB Wired Keyboard

Mice

HP USB Optical Mouse HP USB Hardened Optical Mouse HP USB Universal Mouse

NOTE: Availability may vary by country



Features

SOFTWARE AND SECURITY

HP Support

HP PC Hardware Diagnostics HP Cloud Recovery HP Support Assistant

Internet Security and Antivirus

McAfee LiveSafe (30-day subscription)1

Product Setup

HP JumpStarts

Security Features

Trusted Platform Module (TPM) 2.0 (firmware)^{2,3}

Productivity

Xerox® DocuShare® (90 days free trial offer)4

- 1. 30 day trial period. Internet access required to receive updates. First update included. Subscription required for updates thereafter
- 2. TPM feature will not be supported on machines pre-configured with FreeDOS and Linux
- 3. In selected countries, machines pre-configured with Windows OS will be shipped with TPM disabled.
- 4. Simply sign up and start using Xerox® DocuShare® Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 day free trial period. See visit https://xerox.com/docusharego for details.

POWER

Power Supply

HP Smart 65W External AC power adapter

PORTS/SLOTS

Rear I/O Ports

Two (2) Type-A Hi-Speed USB 480Mbps signaling rate ports

Two (2) Type-A SuperSpeed USB 5Gbps signaling rate ports

One (1) RJ-45 (network) jack

One (1) HDMI 1.4 out connector

One (1) Microphone/Headphone Combo Jack

One (1) DC in power

Bottom I/O Ports

One (1) 3 in 1 Card reader (SD, SDHC, SDXC) (Optional)

Internal I/O Ports

One (1) M.2 PCIe x1 2230 (for WLAN)

One (1) M.2 PCIe x4 2280 for Intel® Core™ / One (1) M.2 PCIe x1 2280 for Intel® Pentium® configurations

One (1) SATA storage connector

Bays

One (1) 3.5" internal storage drive



Features

WEIGHTS & DIMENSIONS

Weight

21.5 Non-Touch Product Weight (Unboxed) Without Stand

5.15 kg, 11.35 lbs

Basic Stand

5.7 kg, 12.57 lbs

21.5 Shipping Weight (Boxed) 8.16 kg, 17.99 lbs

21.5 Shipping Weight (Pallet) 167.61 kg, 369.52 lbs

Dimension

21.5 System Dimensions Without Stand

490.3 x 322.0 x 58.1 mm 19.3 x 12.68 x 2.29 in

Basic Stand

490.3 x 380.74 x 204.51 mm 19.3 x 14.99 x 8.05 in

21.5 Shipping Dimensions (Boxed) 593 x 478 x 243 mm, 23.35 x 18.82 x 9.57 in

21.5 Shipping Dimensions (Pallet) 1186 x 972 x 1569 mm, 46.69 x 38.27 x 61.77 in

21.5 Pallet Quantity (including Touch, Non-Touch) 24



Features

UNIT ENVIRONMENT AND OPERATING CONDITIONS9

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's recirculated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)*

Non-operating: -22° to 140° F(-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude (unpressurized) Operating: 5000m

Non-operating: 50000ft (15240 m)

NOTE: Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label
- Commission Regulation (EC) No 617/2013 (ErP Lot 3)

System Configuration

Energy Consumption (in accordance with US ENERGY STAR® test method)

Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".

115VAC, 60Hz

230VAC, 50Hz

100VAC, 50Hz

NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high



Features

efficiency power supply, and a Microsoft Windows® operating system. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options

Heat Dissipation*

Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off

115VAC. 60Hz 230VAC. 50Hz 100VAC. 50Hz

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

Typically Configured – Idle Fixed Disk - Random writes Longevity and Upgrading

Sound Power Sound Pressure (L_{WAd}, bels) (L_{pAm}, decibels)

Batteries

after the end of production.

This battery(s) in this product comply with EU Directive 2006/66/EC

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years

Batteries used in the product do not contain: Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- Plastics parts weighing over 25 grams used in the product are marked per IS011469 and IS01043.
- This product contains 38.3% post-consumer recycled plastic (by wt.)
- This product is 95.8% recycle-able when properly disposed of at end of life.

Packaging Materials

Material Usage

External: PAPER/Corrugated

Internal: PLASTIC/EPE (Expanded Polyethylene)

PLASTIC/Polyethylene low density

The plastic packaging material contains at least 90% recycled content.

The corrugated paper packaging materials contains at least 80% recycled content. This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- **Asbestos**
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- **Chlorinated Hydrocarbons**

Features

- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail
 packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to:

http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and resell HP equipment.



Features

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certifications:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf





Technical Specifications – Display

ALL-IN-ONE DISPLAY PANEL SPECIFICATIONS

21.5" diagonal FHD IPS anti-glare WLED-backlit (1920 x 1080)

Non-touch

TypeIPS WLED Backlit LCD **Active area (mm)**476.064 x 267.786

Native resolution (HxV) 1920 x 1080

Refresh rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.24795 x 0.24795

Contrast ratio (typical) 1000:1

Brightness (typical) 250nits

Viewing angle (typical) (HxV) 178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with the use of FRC technology

Color gamut (typical)

Anti-glare

Response time (typical)

NTSC 72%

Yes

14ms

Default color temperature Warm (6500K)

NOTE: All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

21.5" diagonal FHD VA anti-glare WLED-backlit (1920 x 1080)

Non-touch

 Type
 VA WLED Backlit LCD

 Active area (mm)
 476.064 x 267.786

 Native resolution (HxV)
 1920 x 1080

Refresh rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.24795 x 0.24795

Contrast ratio (typical)3000:1Brightness (typical)250nitsViewing angle (typical) (HxV)178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with the use of FRC technology

Color gamut (typical) NTSC 72%
Anti-glare Yes

Response time (typical) 18ms

Default color temperature Warm (6500K)

NOTE: All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



204.5 mm

58.74 mm



Technical Specifications – Stand

ALL-IN-ONE STAND SPECIFICATIONS

Articulating Stand
Tilt Angle
Rotation (Swivel)
Pivot
None

490.3 mm

58.10 mm





Technical Specifications – Storage

STORAGE AND DRIVES

500 GB 7200RPM 3.5in SATA HDD

Capacity500 GBRotational Speed7,200 rpmInterfaceSATA 6.0 Gb/s

Buffer Size32 MBLogical Blocks976,773,168Seek Time11 ms (Average)Height1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 3.5in SATA HDD

Capacity1 TBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size64 MB

 Logical Blocks
 1,953,525,168

 Seek Time
 11 ms (Average)

 Height
 1 in/2.54 cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 7200RPM 3.5in SATA HDD

Capacity2 TBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size64 MB

 Logical Blocks
 3,907,029,168

 Seek Time
 11 ms (Average)

 Height
 1.028 in/26.11 mm

 Width (nominal)
 4.0 in/101.6 mm

41° to 131° F (5° to 55°

Operating Temperature ()

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications – Storage

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10q Capacity 256 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 780MB/s **Logical Blocks** 500.118.192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10q Capacity 512 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 860MB/s **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a Capacity 128 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 2800MB/s **Maximum Sequential Write** Up to 600MB/s **Logical Blocks** 250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.





Technical Specifications – Storage

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a Capacity 256GB Height 2.38mm Length 80mm Width 22mm Interface PCIF Gen3 **Maximum Sequential Read** Up to 2700MB/s **Maximum Sequential Write** Up to 1000MB/s **Logical Blocks** 500.118.192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q Capacity 512 GB Height 2.38mm 80mm Length Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications – Storage

HP 9.5mm Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 a)

Write Speeds DVD-R DL - Up to 6X

DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

Read Speeds DVD-RW. DVD+RW - Up to 8X

> DVD-R DL, DVD+R DL - Up to 8X DVD+R. DVD-R - Up to 8X

DVD-ROM DL, DVD-ROM - Up to 8X

CD-ROM, CD-R - Up to 24X

CD-RW - Up to 24X

Access time

(typical reads, including

Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)

settling)

Power

Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

Environmental conditions

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80% (operating - non-condensing)

Maximum Wet Bulb Temperature 84° F (29° C)





Technical Specifications - Audio

HIGH DEFINITION AUDIO

Type Integrated

HD Audio Codec Realtek ALC3247 Audio Codec

Audio I/O Ports Rear 3.5mm combo (microphone/headphone) jack (32 Ohm) supporting CTIA and OMTP style

headset

Microphone(2K Ohm)

Analog Audio Yes

Internal Speaker Amplifier 2W per channel stereo amplifier for the internal speakers only

Internal Speaker Yes - Stereo Speaker

DAC Sampling Rates 44.1 kHz/48 kHz/96 kHz/192 kHz **ADC Sampling Rates** 44.1 kHz/48 kHz/96 kHz/192 kHz



Technical Specifications – Input/Output

INPUT/OUTPUT DEVICES

HP Universal USB Wired Keyboard

Keys 104, 105 layout (depending upon country)

Physical Characteristics

Dimensions (L x W x H)

18.15 x 6.02 x 1.08 in (461 x 153 x 27.4 mm)

Weight 1.32 lb (600g) min

Operating voltage 5 VDC, +/-5%

Power consumption 50mA Max (All LED on)

Electrical System interface USB Type A plug connector

ESD Contact Discharge: 8 KV Air Discharge: 15 KV

EMI - RFI Conforms to FCC rules for a Class B computing device

Keycaps Mid-profile design

Switch actuation 60±10g nominal peak force with tactile feedback

Switch life 10 million keystrokes (Life tester)

Mechanical

Switch type Contamination-resistant switch membrane

Key-leveling mechanisms For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C) Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)
Non-operating humidity 20% to 80% (non-condensing at ambient)

Environmental Operating shock 40 g, six surfaces

Non-operating shock80 g, six surfacesOperating vibration2-g peak accelerationNon-operating vibration4-g peak acceleration

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence

Drop (in box) 30 in (76.2 cm) on concrete, 16-drop sequence

Technical Specifications – Input/Output

HP USB Universal Wired Mouse

Environmental

Dimensions (H x L x W) 4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)

Weight 0.19lb (90g)

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock 50 g, 6 surfaces

Non-operating shock 80 g, 6 surfaces

Operating vibration 2-g peak acceleration
Non-operating vibration 4-g peak acceleration

Operating voltage 5 VDC, +/-5%

Power consumption 50mA Max

Electrical Resolution 800, 1200, 1600 DPI

Tracking speed 31 inch/sec (max)

Tracking acceleration 8G(max), 1G=9.8m/s3

Connector USB 2.0

Mechanical Cable length 6 ft (1.8 m)

Technical Specifications – Input/Output

HP USB Optical Mouse

Environmental

Electrical

Dimensions (H x L x W) 4.53 x 2.50 x 1.40 in (115 x 63.46 x 35.48 mmm)

Weight 0.18lb (80g)

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock 40 g, six surfaces

Non-operating shock 80 g, six surfaces

Operating vibration 2-g peak acceleration

Non-operating vibration 4-g peak acceleration

Operating voltage 5 VDC, +/-5%

Power consumption 50mA Max

Resolution 1,000 DPI

Sensor Pixart PAN3606DL

Tracking speed 30 inch/sec (max)

Tracking acceleration 9G(max), 1G=9.8m/s2

Connector USB 2.0

Mechanical Cable length 6 ft (1.8 m)



Technical Specifications - Networking

NETWORKING/COMMUNICATIONS

Realtek® RTL8111HSH-CG Gigabit Ethernet Controller	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support
		IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ
	NIC Device Driver Name	PCIe GBE Ethernet Family Controller

WLAN*

Realtek RTL8822CE Wi-F	i 5¹ (802.11ac) 2x2 with Bluetooth® M.2		
Wireless LAN Standards	IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac		
	IEEE 802.11d		
	IEEE 802.11e		
	IEEE 802.11h		
	IEEE 802.11i		
	IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
*NOTE: Wireless access point a backwards compatible with prior	nd internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 is or 802.11 specs.		
Interoperability	Wi-Fi® certified		
Frequency Band	802.11b/g/n		
	• 2.402 – 2.482 GHz		
802.11a/n			
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		



***B02.11g. 6.9 12.1 8.2 4.3 6.48 5.4 Mbps ***B02.11a.1 6.5 9.1 7.1 8.2 4.3 6.48 5.4 Mbps ***B02.11a.1 6.5 9.1 7.1 8.2 4.3 6.48 5.4 Mbps ***B02.11a.1 6.5 9.1 7.1 8.2 4.3 6.48 5.4 Mbps ***B02.11a.1 6.5 9.7 7.1 8.2 4.3 6.48 5.4 Mbps ***B02.11a.1 6.5 9.7 7.1 8.2 4.3 6.4 8.5 4.4 Mbps ***B02.11a.1 6.5 9.7 7.1 8.2 4.3 6.4 8.5 4.4 Mbps ***B02.11a.1 6.5 9.7 7.1 8.2 4.3 6.4 Mbps ***B02.11a.1 8.2 8.2 1.2 Mbps.2 - PSK, TKIP, and AES. ***PAP.2 Certification ***PAP.2 Evertification ***IEEE 802.11i ***WAP1 ***WAP2 ***WAP2 ***WAP2 ***WAP2 ***WAP3 ***WAP4 ***WAP3 ***WAP3 ***WAP3 ***WAP3 ***WAP3 ***WAP3 ***WAP3 ***WAP4 ***WAP3 ***WAP3 ***WAP3 ***WAP3 ***WAP4 ***WAP				
Page		• 5.25 – 5.35 GHz		
B02.11b: 1, 2, 5, 5, 11 Mpps				
* 802.11g; G. 9, 12, 18, 24, 36, 48, 54 Mbps		• 5.825 – 5.850 GHz		
* 802.11g; G. 9, 12, 18, 24, 36, 48, 54 Mbps	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
* 802.11a r. 5.9, 12, 18, 24, 36, 48, 54 Mbps *802.11ar. MCS O ~ MCS 15, 120MHz, and 40MHz) *802.11ar. MCS O ~ MCS 15, 120MHz, and 40MHz *802.11ar. MCS O ~ MCS 15, 120MHz, and 40MHz *802.11ar. MCS O ~ MCS 15, 120MHz, and 40MHz *80MHz *802.11a members *802.11a mem		· · · · · · · · · · · · · · · · · · ·		
* 802.11s: MCS O - MCS 15, (20NHz, and 40MHz)		e i i i i i i i i i i i i i i i i i i i		
- 802.11ac: MCSO ~ MCS9, 1CS, and 2SS) (20MHz, 40MHz & 80MHz) Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM - IEEE 64 17 28 bit WEP encryption for a/b/g mode only - AES-CCMP. 128 bit in hardware - 802.1x authentication - WPA, WPA2: 802.1x, WPA-PSK, WPA2-PSK, TKIP, and AES WPA2 certification - IEEE 802.11i - WAPI Network Architecture Models Noaming - IEEE 802.11 compliant roaming between access points Dutput Power³ - 802.11s; +17.5dBm minimum - 802.11s; +18.5dBm minimum - 802.11s; +18.5dBm minimum - 802.11s; +18.5dBm minimum - 802.11s +18.5dBm minimum - 802.11s +18.5dBm minimum - 802.11s +18.5dBm minimum - 802.11s; +17.5dBm minimum		· · · · · · · · · · · · · · · · · · ·		
Direct Sequence Spread Spectrum				
BPSK_QPSK_CKK_16-QAM_64-QAM_256-QAM	Modulation			
IEEE 64 / 128 bit WEP encryption for a/b/g mode only AES-CMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x, WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.111 WAP1 WAP1 WAP1 Metwork Architecture Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points 802.11b: +18.5dBm minimum 802.11a; +18.5dBm minimum 802.11a; +18.5dBm minimum 802.11a; +18.5dBm minimum 802.11a HT40(2.46Hz): +14.5dBm minimum 802.11a HT40(2.46Hz): +15.5dBm minimum 802.11a WH180(5cHz): +15.5dBm minimum 80		· · · · ·		
AES-CCMP. 128 bit in hardware 802.1 x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.111 WAP1 WAP1 Metwork Architecture Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) Infrastructure (Access Point Required) Infrastructure (Access Point Required) Boutput Power3 B02.11b: 18.508m minimum 802.11b: 18.508m minimum 802.11c: 418.508m minimum 802.11c: 418.508m minimum 802.11r HT20(2.4GHz): 415.5d8m minimum 802.11r HT20(2.4GHz): 415.5d8m minimum 802.11r HT20(2.4GHz): 415.5d8m minimum 802.11r HT20(2.4GHz): 415.5d8m minimum 802.11r HT20(3.6Hz): 415.5d8m minimum 802.11r WHT80(56Hz): 415.5d8m minimum 802.11r WHT80(56Hz): 415.5d8m minimum 802.11r WHT80(56Hz): 411.5d8m minimum 802.11r WHT80(56Hz):	Security ²			
* 802.1 x authentication	Julius,			
WPA, WPA2: 802.1x, WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.111 WAPI Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) Roaming IEEE 802.111 compliant roaming between access points Output Power3 802.115: +18.508m minimum 802.116: +18.508m minimum 802.117: +18.508m minimum 802.111 x +18.508m minimum 802.111 x +18.508m minimum 802.111 x +18.508m minimum 802.111 x +170(2.46Hz): +15.508m minimum 802.111 x +170(3.6Hz): +15.508m minimum 802.111 x +170(3.6Hz): +15.508m minimum 802.111 x +170(3.6Hz): +15.508m minimum 802.111 x +171(3.6Hz): +14.508m minimum 802.112 x WHT80(5.6Hz): +11.508m minimum 802.113 x WHT80(5.6Hz): +11.508m minimum 802.114 x WHT80(5.6Hz): +11.508m				
WPA2 certification **IEEE 802.11i **WAPI **WAPI **Ad-hoc (Peer to Peer) **Infrastructure (Access Point Required) **Infrastructure (Access Point Required) **Infrastructure (Access Point Required) **IEEE 802.11 compliant roaming between access points **Boz.11g: +17.5dBm minimum **802.11g: +17.5dBm minimum **802.11n H740(2.4GHz): +15.5dBm minimum **802.11n H740(2.4GHz): +15.5dBm minimum **802.11n H740(5GHz): +15.5dBm minimum **802.11n H740(5GHz): +15.5dBm minimum **802.11a H740(5GHz): +11.5dBm minimum **802.11a H740				
IEEE 802.11 WAPI				
WAPI				
Network Architecture Models Models Models Models Models Models Roaming IEEE 802.11 compliant roaming between access points - 802.11b: +18.5dBm minimum - 802.11a: +18.5dBm minimum - 802.11a: +18.5dBm minimum - 802.11n HT20(2.46Hz): +15.5dBm minimum - 802.11n HT20(2.46Hz): +11.5dBm minimum - 802.11n HT20(5GHz): +11.5dBm minimum - 802.11a VHT160(5GHz): +11.5dBm minimum - 802.11a (PMC): -80 W (WLAN Associated) - (Idle mode: 50 mW (WLAN Associated) - (Idle mo				
Infrastructure (Access Point Required) Roaming IEEE 802.11 compliant roaming between access points	Network Architecture			
IEEE 802.11 compliant roaming between access points				
- 802.11b; +18.5dBm minimum - 802.11b; +17.5dBm minimum - 802.11a; +17.5dBm minimum - 802.11a +18.5dBm minimum - 802.11n HT20(2.4GHz); +15.5dBm minimum - 802.11n HT20(2.4GHz); +15.5dBm minimum - 802.11n HT20(5GHz); +15.5dBm minimum - 802.11n HT20(5GHz); +11.5dBm minimum - 802.11a HT20(5GHz); +11.5dBm minimum - 802.11ac VHT80(5GHz); +11.5dBm maximum - 802.11ac VHT80(5GHz); +11.5dBm maximu				
802.11g: +17.5dBm minimum 802.11n +13.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11a HT20(5GHz): +14.5dBm minimum 802.11ac VHT60(5GHz): +11.5dBm maximum 802.11ac VHT60(5CHz): +11.5dBm maximum 802.11ac VH				
802.11 a.: +18.5dBm minimum	output Power			
*802.11n HT40(2.4GHz): +14.5dBm minimum *802.11n HT40(5GHz): +15.5dBm minimum *802.11n HT40(5GHz): +14.5dBm minimum *802.11ac VHT160(5GHz): +11.5dBm minimum *802.11ac VHT160(5GHz): +11.5dBm minimum *802.11ac VHT160(5GHz): +11.5dBm minimum *802.11ac VHT160(5GHz): +11.5dBm minimum *Receive mode: 1.6 W *Idle mode (PSP) 180 mW (WLAN Associated) *Idle mode: 50 mW (WLAN Associated) *Idle mode: 50 mW (WLAN unassociated) *Idle mode: 50 mW (WLAN unassociated) *Idle mode: 50 mW (WLAN unassociated) *Receiver Standby/Modern Standby: 10mW *Radio disabled: 8 mW *ACPI and PCI Express compliant power management *802.11 compliant power saving mode *Receiver Sensitivity* *802.11b, 1Mbps: -93.5dBm maximum *802.11b, 1Mbps: -84dBm maximum *802.11a/g, 6Mbps: -86dBm maximum *802.11a/g, 54Mbps: -72dBm maximum *802.11a/g, 54Mbps: -72dBm maximum *802.11a, MCS0: -84dBm maximum *802.11a, MCS0: -84dBm maximum *802.11ac, MCS0: -80BBm maximum *802.11ac, MCS0: -80BBmm maximum *802.11ac, MCS0: -80BBmm maximu				
*802.11n HT20(5GHz): +15.5dBm minimum *802.11a VHT80(5GHz): +14.5dBm minimum *802.11a VHT80(5GHz): +11.5dBm minimum *802.11a VHT160(5GHz): +11.5dBm minimum *802.11a VHT160(5GHz): +11.5dBm minimum *802.11a VHT160(5GHz): +11.5dBm minimum *Receive mode: 1.6 W *Idle mode: 5.0 W *Receive mode: 1.6 W *Idle mode: 50 mW (WLAN Associated) *Idle mode: 50 mW (WLAN unassociated) *Connected Standby/Modern Standby: 10mW *Radio disabled: 8 mW *Power Management *ACPI and PCI Express compliant power management *802.11 compliant power saving mode *Receiver Sensitivity* *802.11b, 11Mpps: -93.5dBm maximum *802.11a/g, 6Mbps: -93.5dBm maximum *802.11a/g, 54Mbps: -72dBm maximum *802.11a/g, 54Mbps: -72dBm maximum *802.11a, MCS07: -67dBm maximum *802.11a, MCS07: -67dBm maximum *802.11a, MCS07: -67dBm maximum *802.11a, MCS05: -84dBm maximum *802.1				
- 802.11n HT40(5GHz): +14.5dBm minimum - 802.11ac VHT160(5GHz): +11.5dBm minimum - 802.11ac W - 8cecive mode: 1.6 W - 1dle mode (PSP) 180 mW (WLAN Associated) - 1dle mode: 50 mW (WLAN unassociated)				
802.11ac VHT80(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum 802.60				
- 802.11ac VHT160(5GHz): +11.5dBm minimum Power Consumption • Transmit mode:2.0 W • Receive mode:1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode:50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW Power Management ACPI and PCI Express compliant power management 802.11 compliant power saving mode Receiver Sensitivity 802.11b, 11Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS07: -67dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS0: -84dBm aximum 802.11ac, MCS0: -84dBm aximum 802.11ac, MCS0: -84dBm diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Derating Voltage 14° to 158° F (-10° to 70° C) Non-operating 14° to 158° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)				
Power Consumption • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW Power Management ACPI and PCI Express compliant power management 802.11 compliant power saving mode Receiver Sensitivity 802.11b, 11Mbps: -93.5dBm maximum 802.11a/g, 6Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a, MCS07: -67dBm maximum 802.11a, MCS07: -67dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum Form Factor High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Derating Voltage 3.3v +/-9% Temperature Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)				
Receive mode: 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled: 8 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode Receiver Sensitivity 802.11b, 1Mbps: -93.5dBm maximum 802.11a/g, 6Mbps: -84dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a, MCS07: -67dBm maximum 802.11a, MCS07: -67dBm maximum 802.11a, MCS07: -67dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm completed by the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Derating Voltage Temperature Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)	Dower Consumption			
• Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode:50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW Power Management ACPI and PCI Express compliant power management 802.11 compliant power saving mode Receiver Sensitivity 802.11b, 11Mbps: -93.5dBm maximum 802.11a/g, 6Mbps: -84dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS05: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum Antenna type High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Operating 14° to 158° F (-10° to 70° C) Non-operating 140° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)	Power Consumption			
• Idle mode:50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode Receiver Sensitivity 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS07: -67dBm maximum 802.11ac, MCS9: -59dBm maxim				
• Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode Receiver Sensitivity ⁴ 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS07: -67dBm maximum 802.11ac, MCS0: -84dBm maximum 80				
• Radio disabled: 8 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps: -93.5dBm maximum 802.11a, 1Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a, MCS07: -67dBm maximum 802.11a, MCS05: -64dBm maximum 802.11a, MCS05: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum Antenna type High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Operating Voltage Temperature Operating 14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)		·		
ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS07: -67dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum Antenna type High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Operating Voltage 7 ye 2230: 2.8g Operating 14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)				
802.11 compliant power saving mode 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS07: -67dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -30dBm maximum 802.11ac, MCS9: -3	Power Management			
Receiver Sensitivity ⁴ 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS07: -67dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -54dBm maximu	rowei management			
802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS07: -67dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -84dBm maximum 802.11ac, MCS9: -64dBm maximum 802.11ac, MCS9: -59dBm ma	Possivor Sonsitivity ⁴	1 1		
802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm max	Receiver Sensitivity			
802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Operating Voltage Temperature Operating 14° to 158° F (-10° to 70° C) Non-operating 14° to 158° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)				
802.11n, MCS07: -67dBm maximum 802.11n, MCS05: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Operating Voltage 3.3v +/- 9% Temperature Operating 14° to 158° F (-10° to 70° C) Non-operating 10% to 90% (non-condensing)				
802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ac, MCS9: -59dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Operating Voltage 3.3v +/- 9% Temperature Operating 14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)				
802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Operating Voltage 3.3v +/- 9% Temperature Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)				
802.11ac, MCS9: -59dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Type 2230: 2.8g Operating Voltage 3.3v +/- 9% Temperature Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)				
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communications and Bluetooth communications Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Operating Voltage 3.3v +/- 9% Temperature Operating Non-operating -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)	Antenna type			
Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm Weight Type 2230: 2.8g Operating Voltage 3.3v +/- 9% Temperature Operating Non-operating Non-operating -40° to 176° F (-40° to 80° C) Humidity Operating Non-condensing				
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Operating Voltage 3.3v +/- 9% Temperature Operating Non-operating Non-operating 14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing)				
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Non-operating –40° to 176° F (–40° to 80° C) Humidity Operating 10% to 90% (non-condensing)				
Humidity Operating 10% to 90% (non-condensing)	Temperature	'		
		, ,		
Non-operating 5% to 95% (non-condensing)	Humidity			
		Non-operating 5% to 95% (non-condensing)		



Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	

- 1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. 2. Must be configured at time of purchase.
- 2. Check latest software/driver release for updates on supported security features.
- 3. Maximum output power may vary by country according to local regulations.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

(Of Divinioudiation).			
HP Integrated Module with Blue	etooth 4.0/4.1/4.2/5.0 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)		
	BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps		
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.		
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW		
Bloods at h® Caftoniana Company d	Selective Suspend 17 mW		
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
	ETS 300 328, ETS 300 826		
	Low Voltage Directive IEC950		
	UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance		
	LE Link Layer Ping		
	LE Dual Mode		
	LE Link Layer		
	LE Low Duty Cycle Directed Advertising		
	LE L2CAP Connection Oriented Channels		
	Train Nudging & Interlaced Scan		
	BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full		
	LE Privacy 1.2 –Link Layer Privacy		
	LE Privacy 1.2 –Enik Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies		
	LE Data Packet Length Extension		
	FAX Profile (FAX)		
	Basic Imaging Profile (BIP)2		
	Headset Profile (HSP)		
	Hands Free Profile (HFP)		
	Advanced Audio Distribution Profile (A2DP)		



	(802.11ac) 1x1 with Bluetooth® M.2		
Wireless LAN Standards	IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac		
Interoperability	Wi-Fi® certified		
Frequency Band	802.11b/g/n		
	• 2.402 – 2.482 GHz		
	802.11a/n		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)		
Modulation	Direct Sequence Spread Spectrum		
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ²	• IEEE 64 / 128 bit WEP encryption for a/b/g mode only		
	AES-CCMP: 128 bit in hardware		
	• 802.1x authentication		
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.		
	WPA2 certification		
	• IEEE 802.11i		
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite		
	• WAPI		
Network Architecture	Ad-hoc (Peer to Peer)		
Models	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power ³	• 802.11b: +14dBm minimum		
-	• 802.11g: +12dBm minimum		
	• 802.11a: +12dBm minimum		
	• 802.11n HT20(2.4GHz): +12dBm minimum		
	• 802.11n HT40(2.4GHz): +12dBm minimum		
	• 802.11n HT20(5GHz): +10dBm minimum		
	• 802.11n HT40(5GHz): +10dBm minimum		
	• 802.11ac VHT80(5GHz): +10dBm minimum		
Power Consumption	Transmit mode2.0 W		
•	Receive mode 1.6 W		
	• Idle mode (PSP) 180 mW (WLAN Associated)		
	• Idle mode 50 mW (WLAN unassociated)		
	Connected Standby 10mW		
	Radio disabled 8 mW		
Power Management	ACPI and PCI Express compliant power management		
3	802.11 compliant power saving mode		
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum		
	802.11b, 11Mbps: -84dBm maximum		
	802.11a/g, 6Mbps: -86dBm maximum		
	802.11a/g, 54Mbps: -72dBm maximum		
	802.11n, MCS07: -67dBm maximum		
	802.11n, MCS15: -64dBm maximum		
	802.11ac, MCS0: -84dBm maximum		



	802.11ac, MCS9: -	802.11ac, MCS9: -59dBm maximum		
Antenna type	High efficiency an	High efficiency antenna.		
	One embedded du	One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN		
	communications a	communications and Bluetooth communications		
Form Factor	PCI-Express M.2 M	PCI-Express M.2 MiniCard		
Dimensions	Type 2230: 2.3 x 2	Type 2230: 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230: 2.8g	Type 2230: 2.8g		
Operating Voltage	3.3v +/- 9%	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)		
	Non-operating	-40° to 176° F (-40° to 80° C)		
Humidity	Operating	10% to 90% (non-condensing)		
	Non-operating	5% to 95% (non-condensing)		
Altitude	Operating	0 to 10,000 ft (3,048 m)		
	Non-operating 0 to 50,000 ft (15,240 m)			
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- 3. Maximum output power may vary by country according to local regulations.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

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Bluetooth® Specification	4.0/4.1/4.2 Compliant		
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Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension		



Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	
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Technical Specifications - Power

POWER

Efficiency 65W EPS, 88% average efficiency at 115V & 89% at 230Vac

Operating Voltage Range 90Vac~264Vac **Rated Voltage Range** 100Vac~240Vac **Rated Line Frequency** 50Hz~60Hz **Operating Line Frequency** 47Hz~63Hz **Rated Input Current** ≤1.6A **Rated Input Current with Energy** ≦1.6A

Efficient* Power Supply

DC Output +19.5V

Current Leakage (NFPA 99: 2102) Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as

required for Non-Patient Electrical Appliances and Equipment used in a patient care facility or

that contact patients in normal use. Per section 10.3.5.1.

Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-Patient Electrical Appliances and Equipment used in a patient care

facility or that contact patients in normal use. Per section 10.3.5.1.

Dimensions 102 x 55 x 30 mm



Technical Specifications - Additional Features

ADDITIONAL FEATURES

Description

SMART Technology (Self-Monitoring, Analysis and Reporting Technology)

Allows hard drives to monitor their own health and to raise flags if imminent failures

were predicted





Summary of Changes

SUMMARY OF CHANGES

Date of change:	Version History:		Description of change:
March 13, 2020	V1 to V2	Update	First page call out number 1 corrected.
June 16, 2020	V2 to V3	Update	Rear image call outs and rear I/O ports updated
July 20, 2020	V3 to V4	Update	Rear image call out #9 and ports section speed corrected
September 24, 2020	V4 to V5	Addition	Xerox® DocuShare® and footnote to software section.
December 3, 2020	V5 to V6	Removal	Energy Star and EPEAT on Page 3, Page 28
October 29, 2021	V6 to V7	Update	OS section
December 15, 2021	V7 to V8	Update	Windows 11 update
May 23, 2022	V8 to V9	-	Document Name, at a glance, OS´s, processors, graphics and memory
			sections updated
June 21, 2022	V9 to V10	Update	Environmental table certifications updated
July 29, 2022	V10 to V11	Update	SD card reader as optional

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